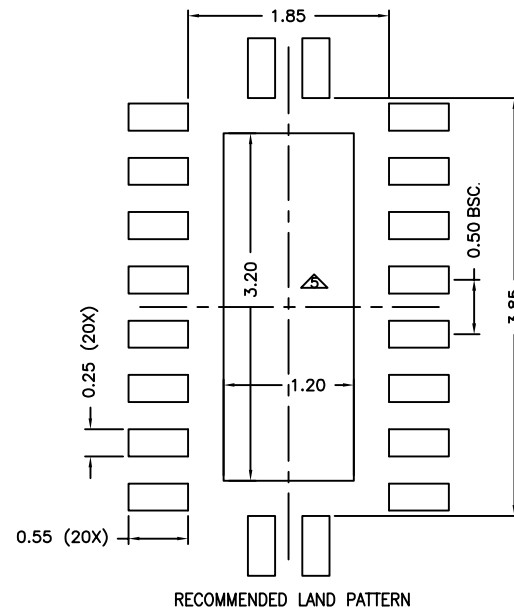
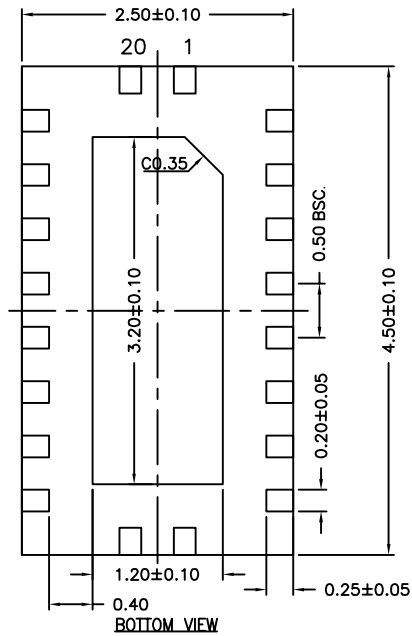


RECOMMENDED STENCIL DESIGN for EPAD
(0.125mm THICK STENCIL)



NOTE :

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO-241
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA (MESH STENCIL DESIGN IS RECOMMENDED).



PERICOM[®] A PRODUCT LINE OF DIODES INCORPORATED
ENABLING SERIAL CONNECTIVITY

DATE: 11/07/17

DESCRIPTION: 20-Contact, Very Thin Quad Flat No-Lead (TQFN)

PACKAGE CODE: ZBB (ZBB20)

DOCUMENT CONTROL #: PD-2232

REVISION: --